

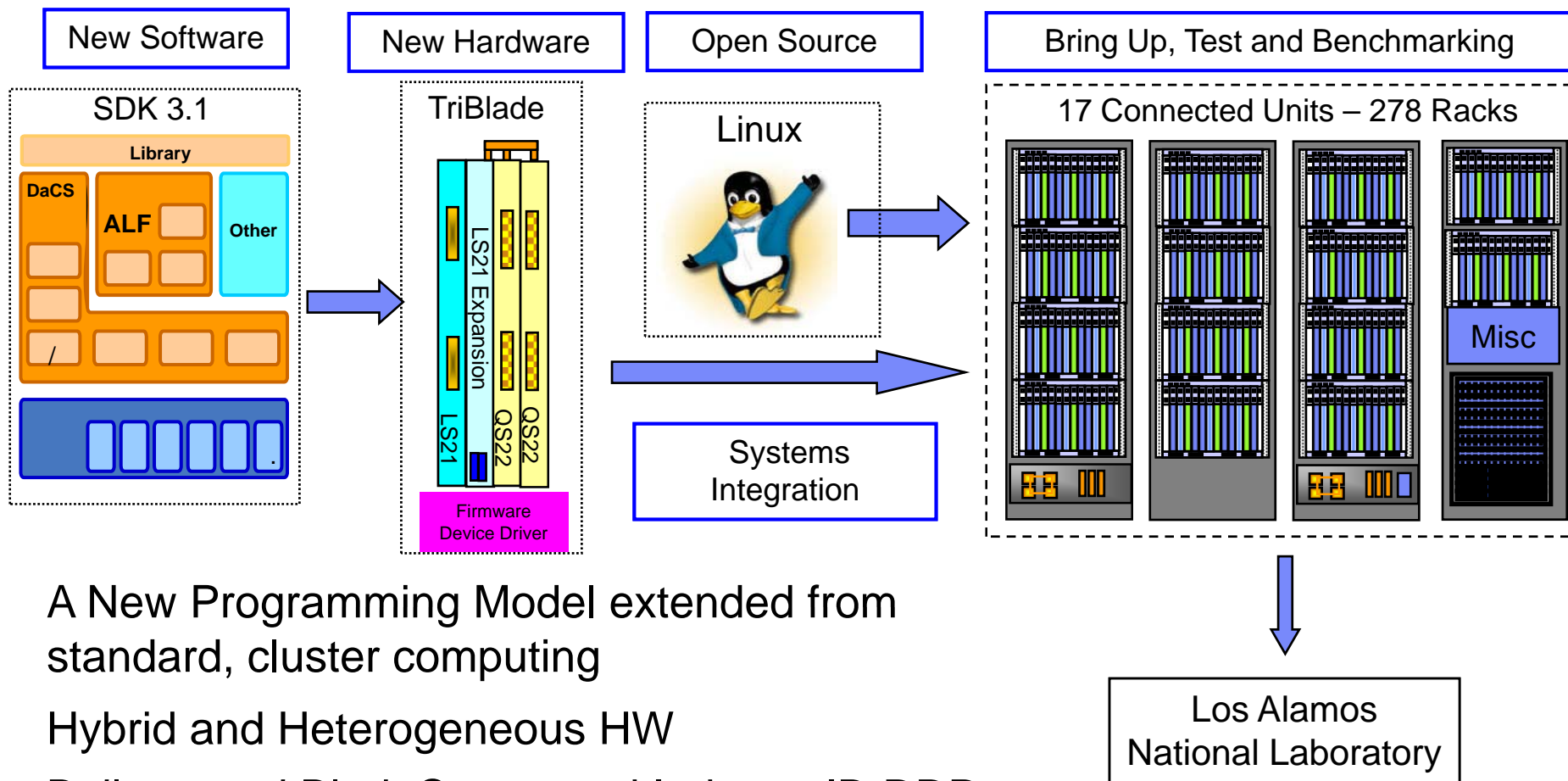


Exascale Systems

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Opinions expressed are the author's *personal* opinions and should not be construed as being endorsed by IBM

Today: LANL's RoadRunner*



- A New Programming Model extended from standard, cluster computing
- Hybrid and Heterogeneous HW
- Built around BladeCenter and Industry IB-DDR

T/V	N	NB	P	Q	Time	Gflops
WR13C2C8	2236927	128	68	180	7269.80	1.026e+06

The Near Future (1): Blue Waters

- **Highly Productive sustained petaflop system by mid-2011**
 - POWER7 multicore chips
 - A large, high-performance memory subsystem, to enable the solution of memory-intensive problems.
 - A low-latency, high-performance interconnect, to facilitate scaling to large numbers of cores.
 - A high-performance I/O subsystem, to enable the solution of data-intensive problems.
 - High reliability, to ensure that the most challenging problems can be addressed.

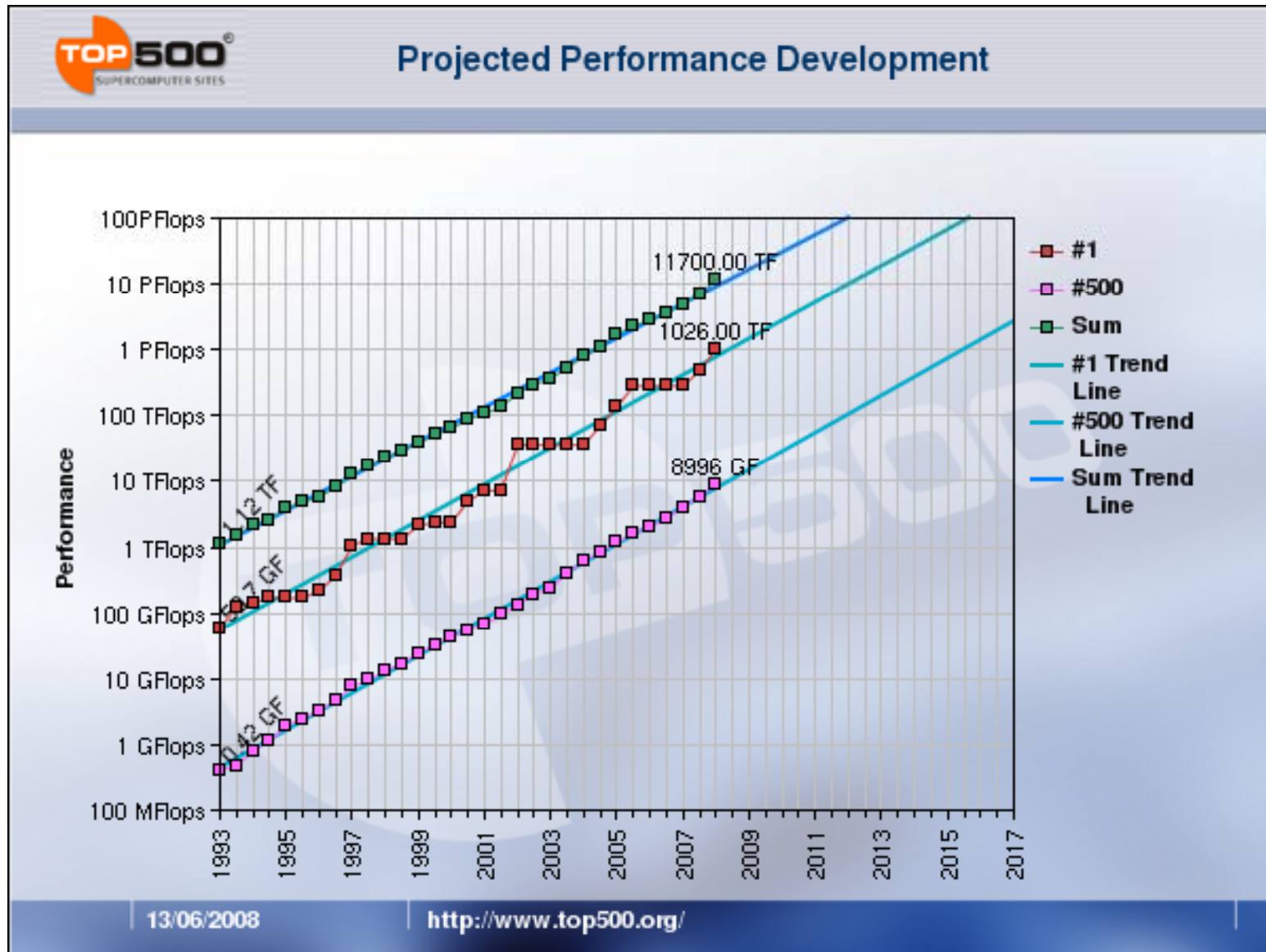


The Near Future (2): BlueGene/Q

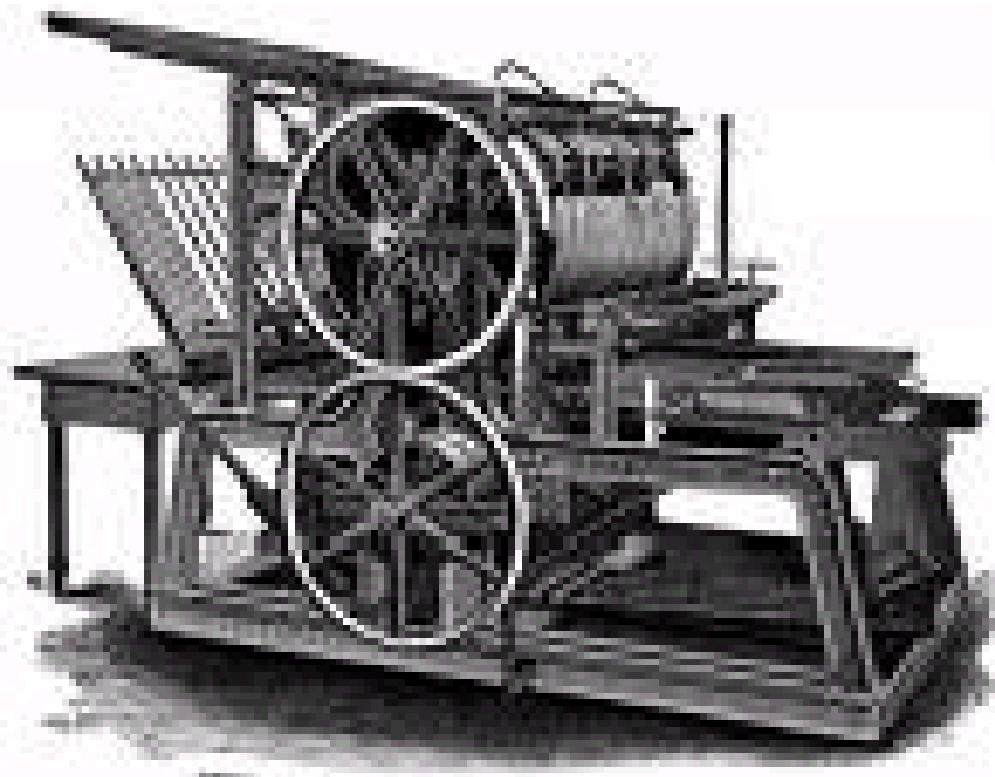
- Mission driven partnership with DOE/NNSA/OoS
 - Push state of the art by >10x
 - Scales > 10PFLOPs
 - Radically new node and system architecture
 - Leverage Blue Gene OS communities
 - Grand challenge science stresses
 - Production system for classified codes



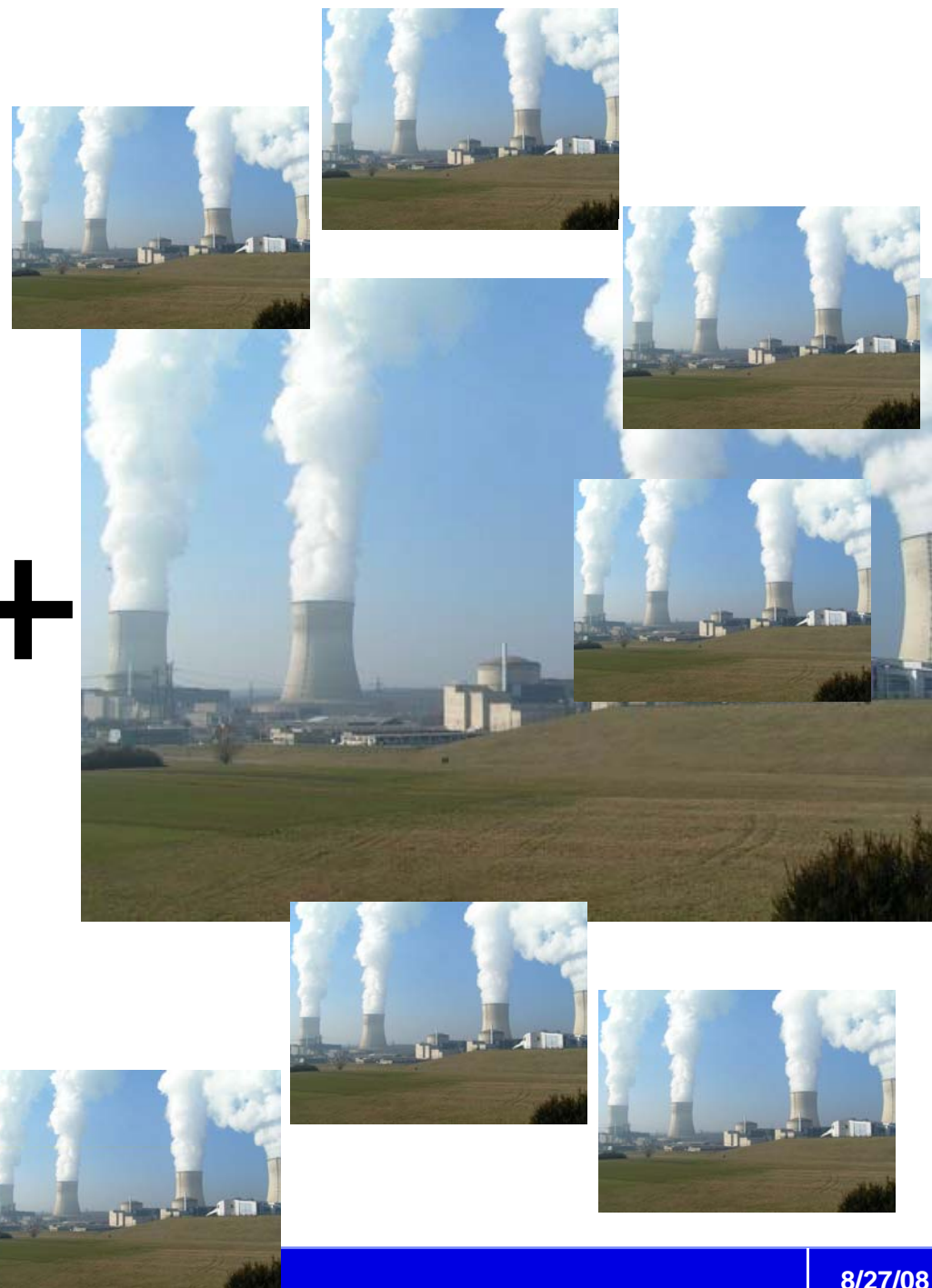
Trends pointing to Exaflop systems



The Quick Answer



+



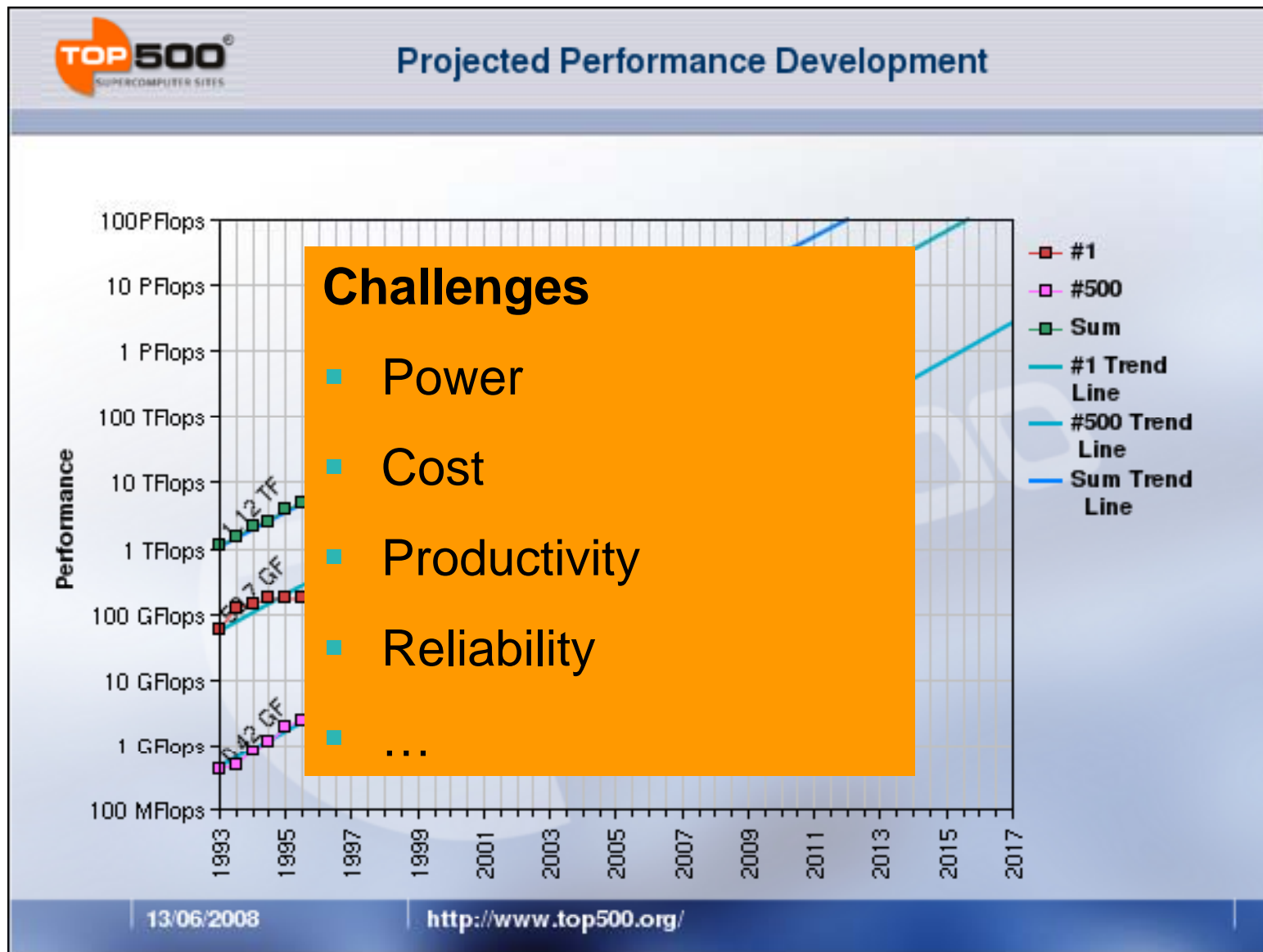
What will an Exaflop system look like?

■ Peak of an Exaflop

■ Reasonable characteristics:

- Power: 100 to 300 MW → **Must bring down to 30 to 50 MW**
 - Power cost is ~ \$1M/MW/year → 1 Exaflop @ 100 MW = \$100 million per year!!!
 - Power needs to go down in order to make operational costs affordable
- “Memory” capacity: 30 to 100 PBytes
- Productivity: Sustained similar to (or better than) systems in use today
- Reliability: MTBF of at least multiple days
- Storage capacity: ~ 1 Exabyte

Getting to an Exaflop: Challenges



Power: A look at the Green500 list

Green 500 Rank	Site	Manufacturer	Computer	Mflops Per Watt	Total Power (kW)	TOP500 Rank
1	IBM Germany	IBM	BladeCenter QS22 Cluster, PowerXCell 8i 3.2 Ghz, Infiniband	488.14	22.76	324
1	Fraunhofer ITWM	IBM	BladeCenter QS22 Cluster, PowerXCell 8i 3.2 Ghz, Infiniband	488.14	18.97	464
3	DOE/NNSA LANL	IBM	BladeCenter QS22/LS21 Cluster, PowerXCell 8i 3.2 Ghz / Opteron DC 1.8 GHz , Voltaire Infiniband	437.43	2345.5	1
4	Argonne National Laboratory	IBM	Blue Gene/P Solution	371.75	31.5	304
4	Dublin Institute for Advanced Studies/ICHEC	IBM	Blue Gene/P Solution	371.75	31.5	305

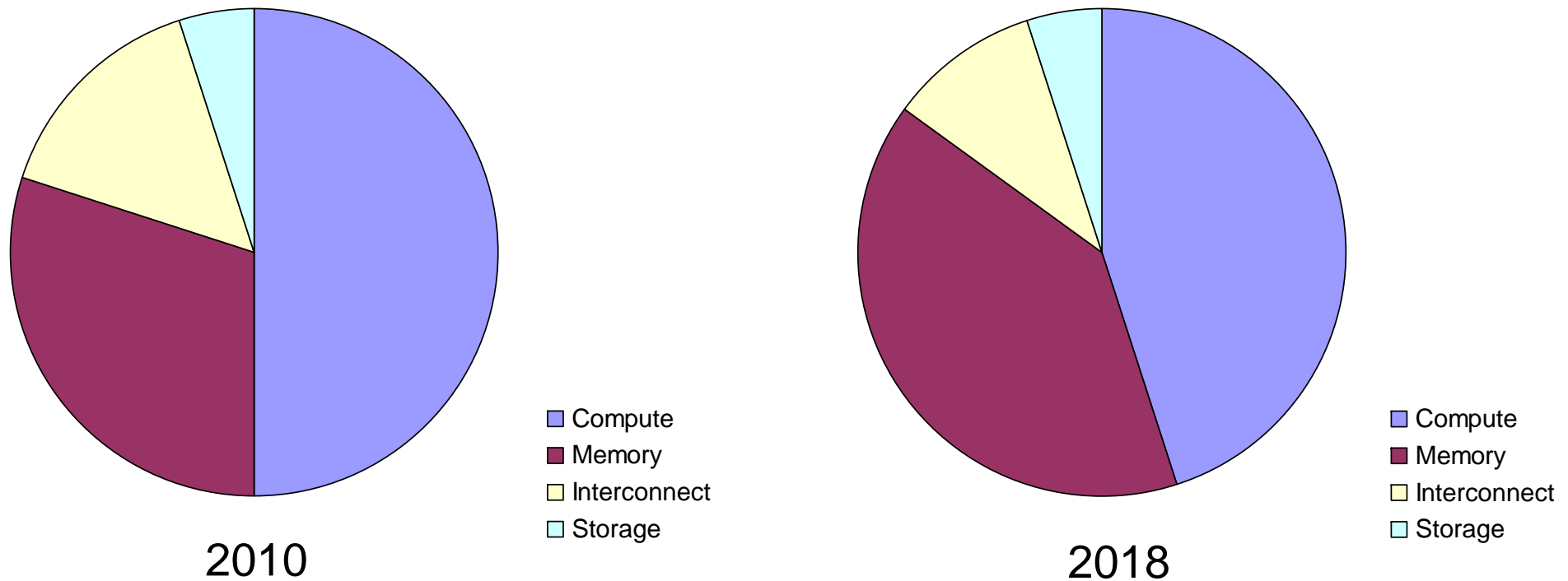
Source: www.green500.org

Fact: 39 out of the first 40 entries in the list are IBM systems
76% of the first 100 entries are IBM systems

To keep total power within 100 MW (!!!!!!!), MFLOPS/Watt would have to be 10000

System power distribution

- Compute and memory generally dominate power today
- But we will be in serious trouble if we let the trends continue

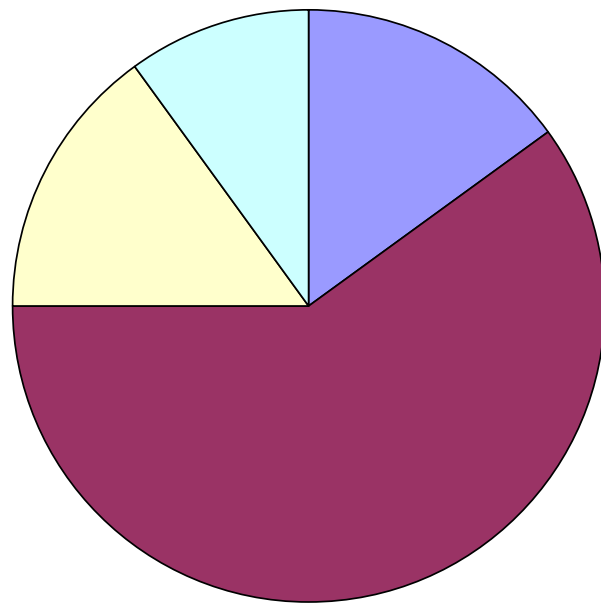


➔ Need new approaches to compute and memory, must contain interconnect

Assumptions: 0.125 B/F DDR memory, localized interconnect ➔ controlled optics, compute trends continue

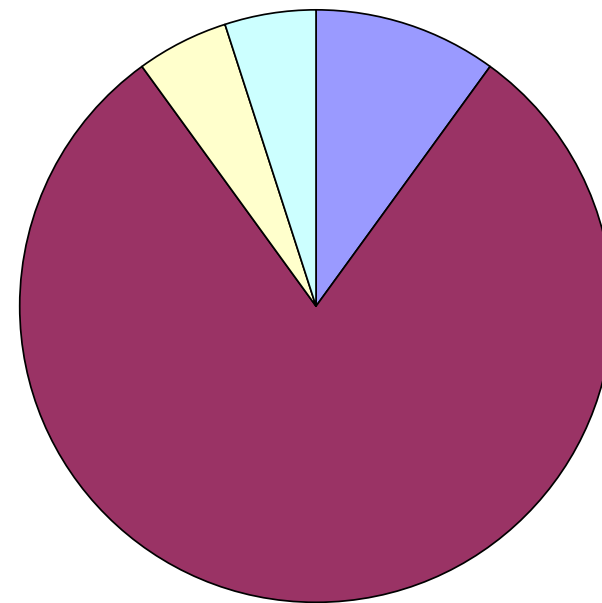
System cost distribution

- Compute and memory generally dominate power today
- But we will be in serious trouble if we let the trends continue



2010

■ Compute
■ Memory
■ Interconnect
■ Storage



2018

■ Compute
■ Memory
■ Interconnect
■ Storage

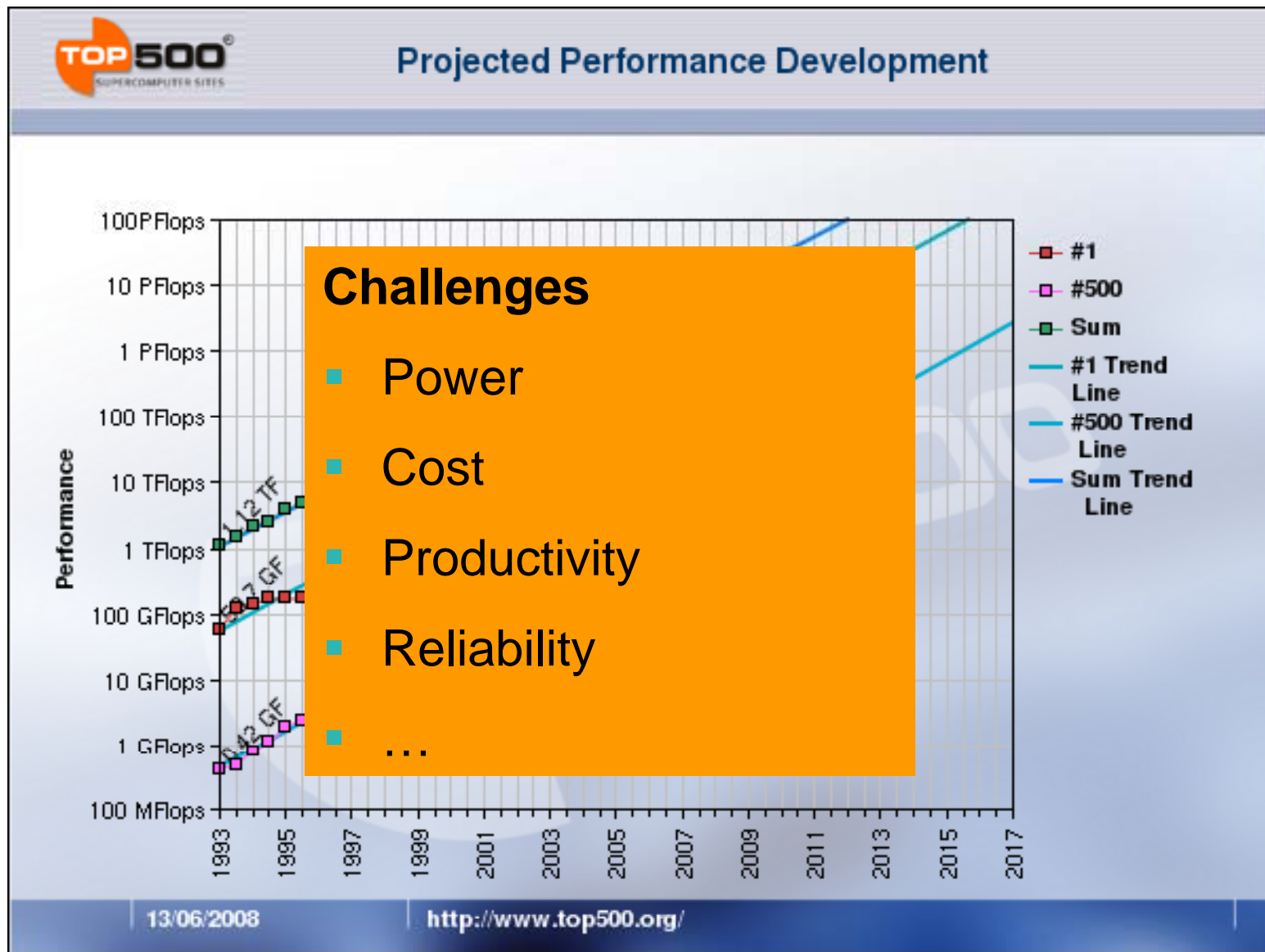
➔ First problem is memory

Assumptions: 0.125 B/F DDR memory, localized interconnect ➔ controlled optics, compute trends continue

Reliability

- The LANL Roadrunner* has close to 100K Cell engines (8 to a Cell chip)
- The ½ PFLOP BG/L has over 200K processors
- Compute frequencies are unlike to increase significantly → we will likely have an atrociously large number of *compute elements* in exaflop systems.
- How to handle compute failures?
- What about memory failures?
- What about optics failures?

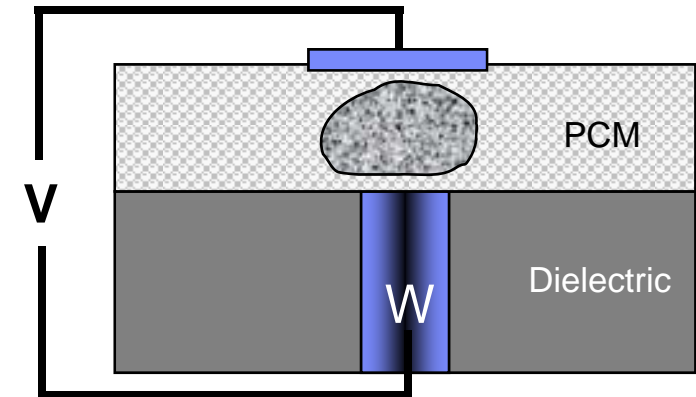
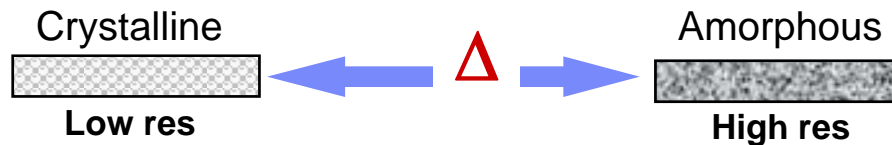
Getting to an Exaflop: Challenges



Enabling Technologies

Phase Change Memory

Based on Chalcogenide Glass material property



Heat applied via Joule Heating – an accompanying transistor or diode drives a current through the material

Overview

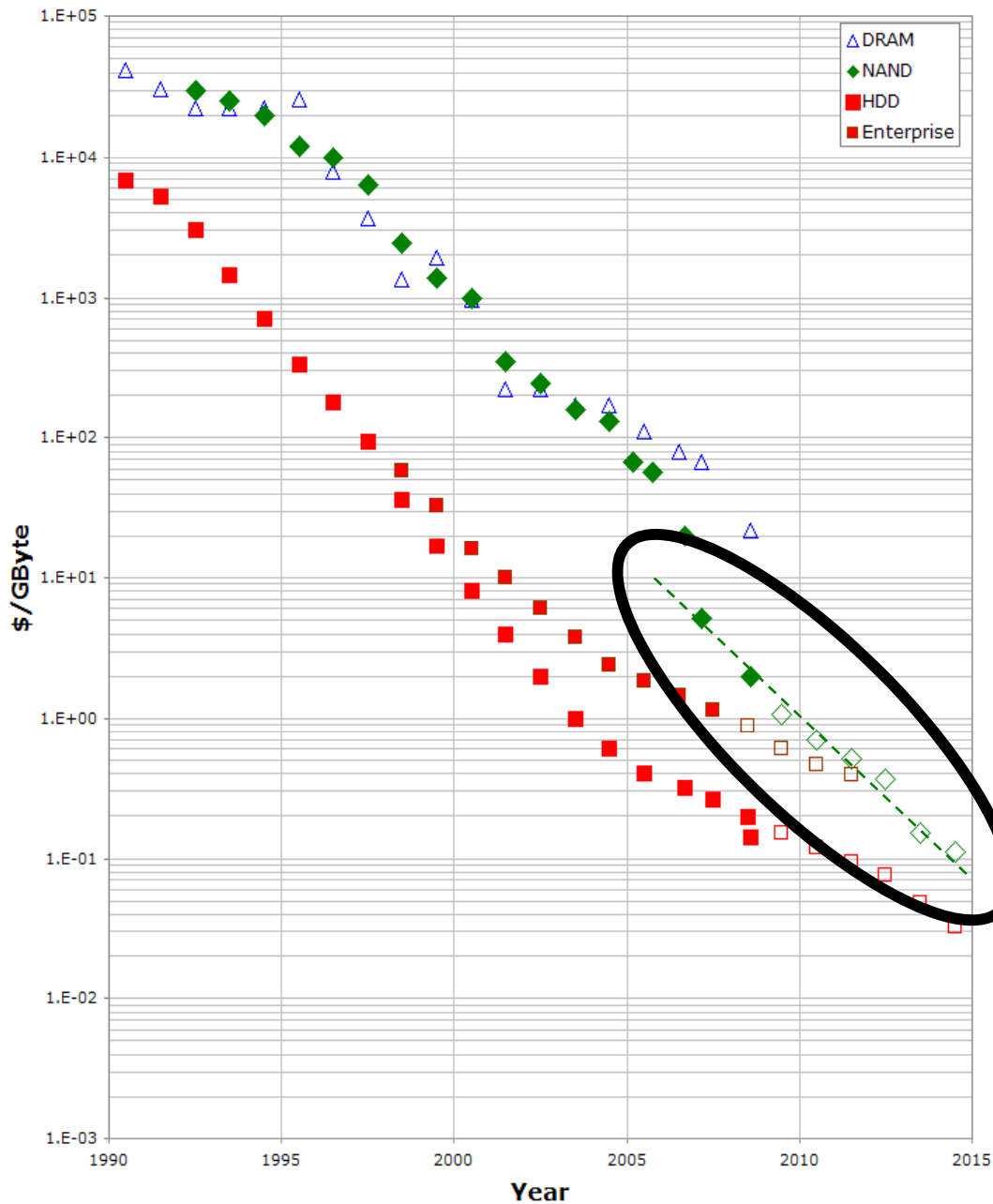
- Has been used in CD-RW and DVD-RW technologies
- Can be switched between Crystalline and Amorphous states with the addition of heat.
- Heat applied via Joule Heating – an accompanying transistor or diode drives a current through the material
- Non-Volatile, true Random Access capability
- Density limited by the size of the drive transistor or diodes and not the memory cell size

Details of Switching Process

- Drastic difference in resistance (ratios > 1000):
- SET – amorphous to crystalline - requires heating to ~ 320C (above crystalline temp but below melt temp) and holding until recrystallization can occur ← Speed limiting step - published data indicates 50 ns (IEDM 2003)
- RESET – crystalline to amorphous – Requires heating to ~ 650C (above the melt temp) and doing a quick quench to lock in the amorphous state ← Power limiting step - published data indicates 30 ns pulse length to get to 10^{12} cycles

Source: Stefanie Chiras, IBM Research

Storage Class Memory: Game changer for cost?

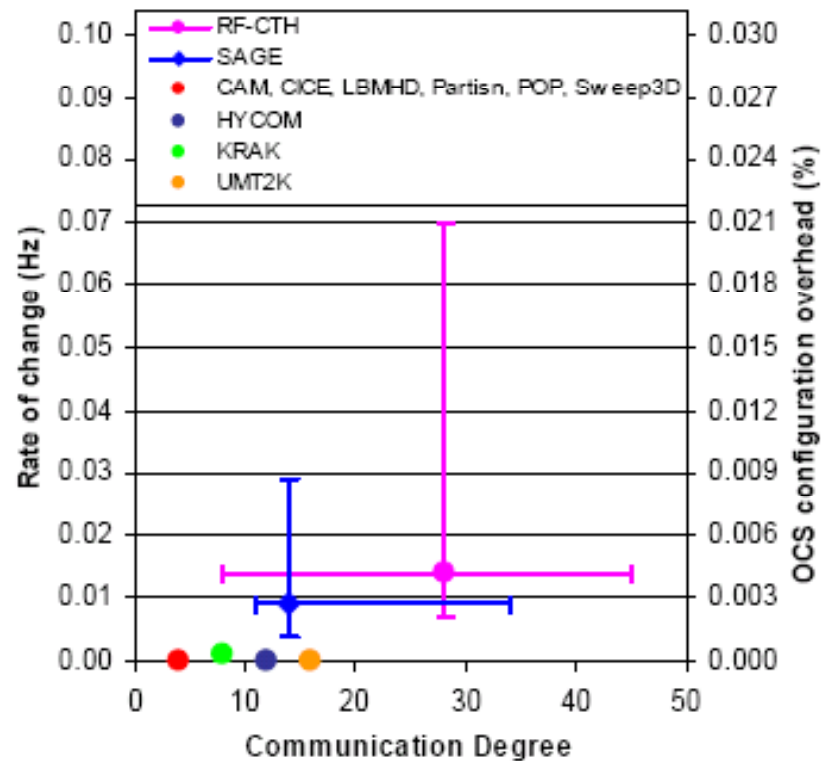


■ NAND assumes ITRS Road Map

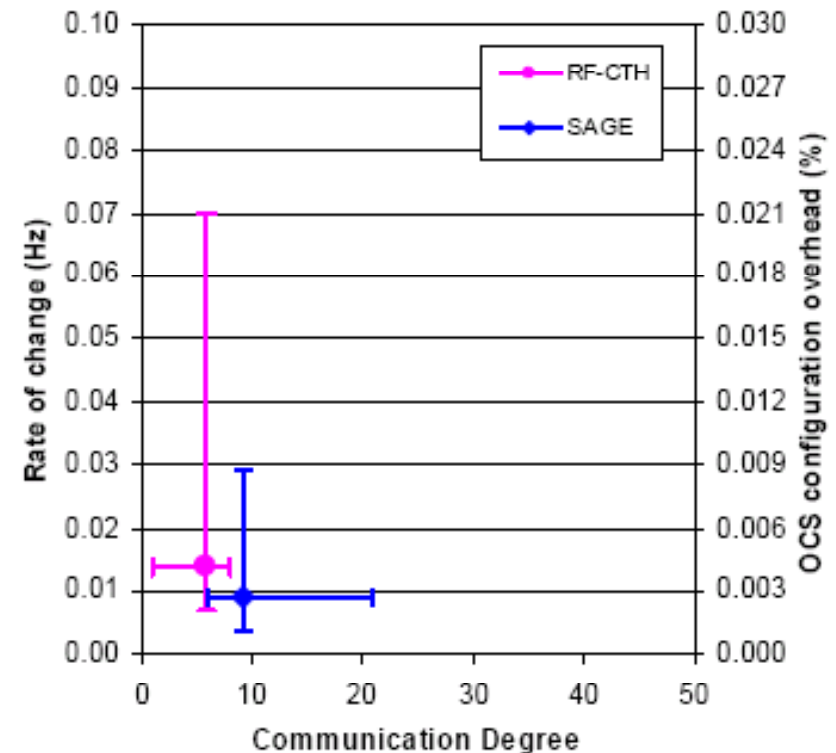
	½Pitch nm	# of bits	# of 3D layers
2008	45	2	1
2009	40	3	1
2010	36	4	1
2011	32	4	1
2012	28	4	1
2013	25	4	2
2014	22	4	2
2015	20	4	2

Source: Chung Lam, IBM Research

Interconnect: Communication Locality



Before threshold filtering



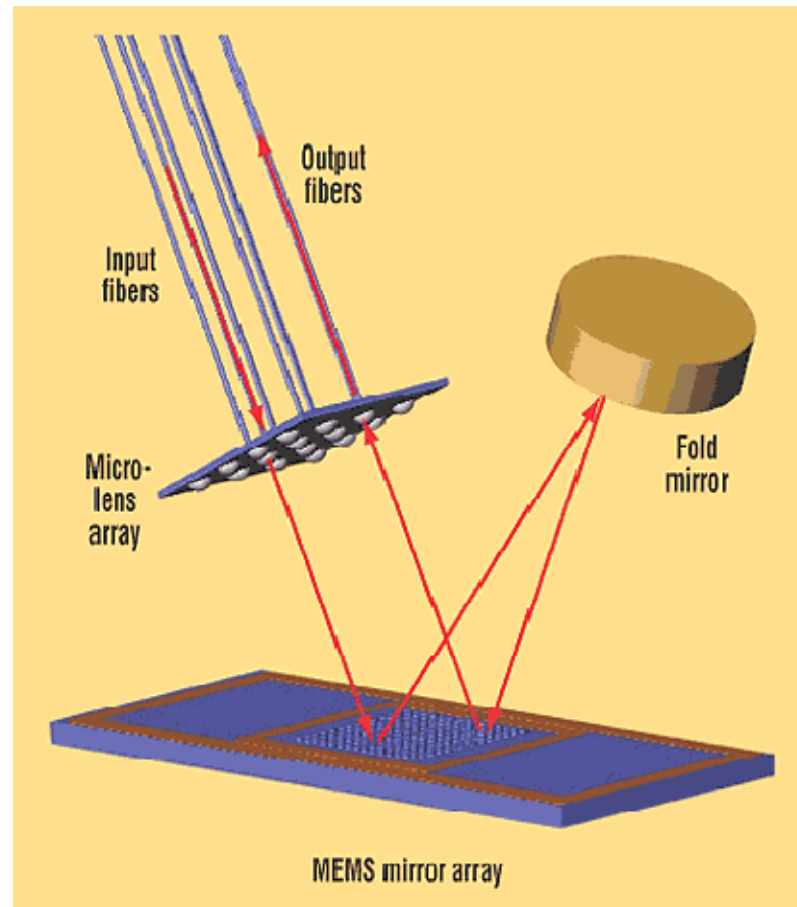
After threshold filtering

Over a large range of investigated *scientific* workloads, most communication is:

- Localized
- Slow-varying in terms of partner assignments

Source: "On the Feasibility of Optical Circuit Switching for High-Performance Computing Systems", Kevin Barker et. al., in SC 2005

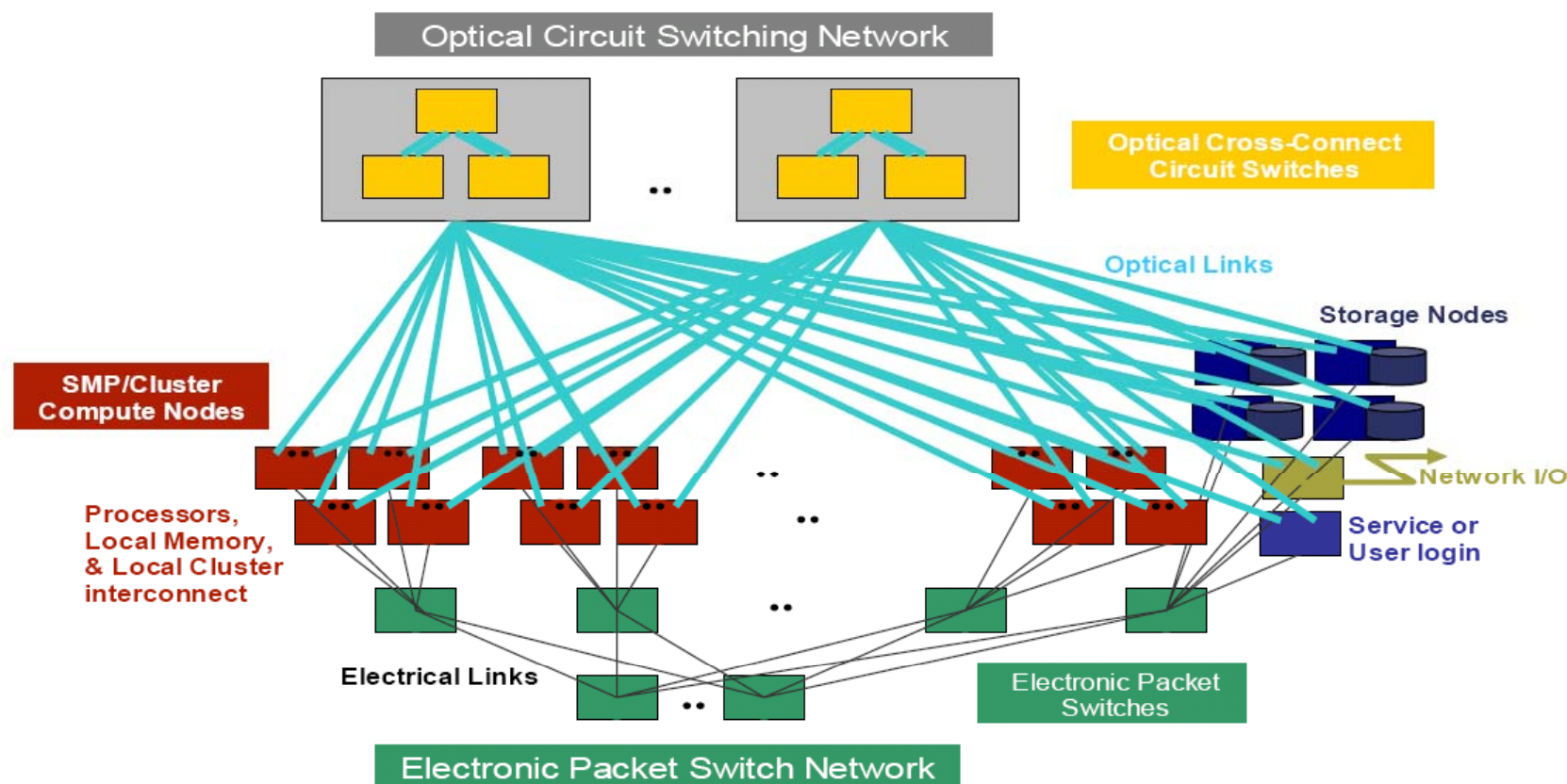
Optical Circuit Switches



Source: http://electronicdesign.com/Files/29/5942/Figure_02.gif

Interconnect Structure

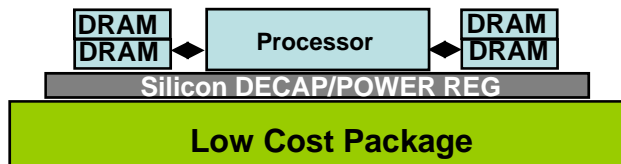
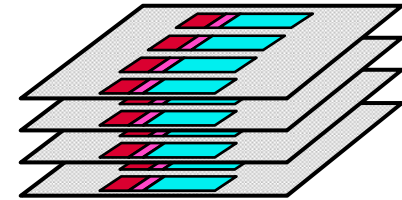
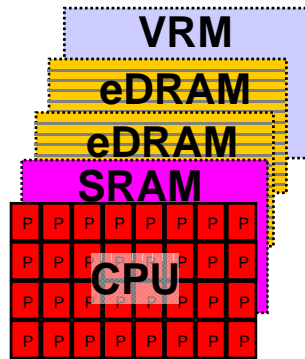
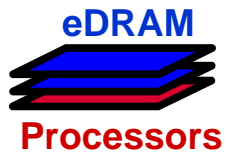
- Optics-based, but what if we exploit locality?
- Possibility: Leverage optical *circuit switching* technologies



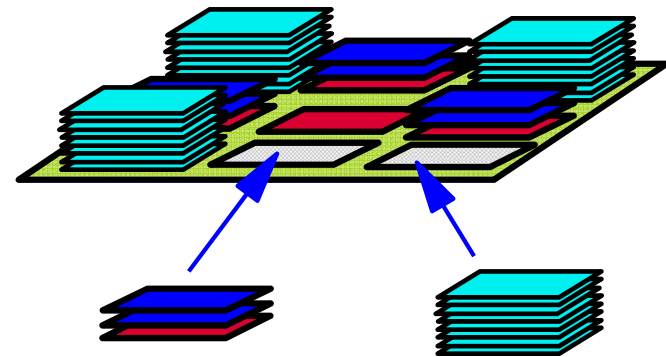
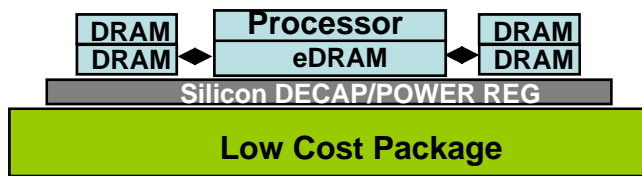
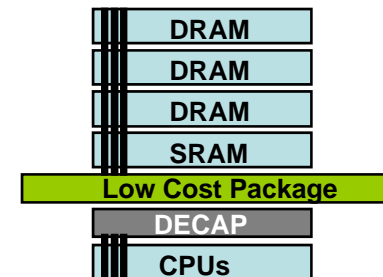
< this does not bode well for spectral codes and FFTs >

Source: "On the Feasibility of Optical Circuit Switching for High-Performance Computing Systems", Kevin Barker et. al., in SC 2005

Cost and Power → 3D Integration



What new systems
can 3D enable?



Compute Processors

- **Frequency likely to remain around 4 GHz**
 - Probably 18nm technology
- **Huge number of transistors possible: 30B to 50B**
 - Depends on cost and commercial viability
 - Large number of cores/compute engines/accelerators
- **High degree of 3D integration**
 - Onboard eDRAM
 - PCM integration needs work
- **Latencies and Bandwidth**
 - Latencies depend on memory technology characteristics
 - High-speed elastic interfaces
 - ???

Strawman Exaflop System(s)

- **Multitude of 3-4 GHz compute cores per chip**

- Sea of engines with control processors, smaller caches, interconnects (optics) integrated on chip, contained cache coherence

- **Memory**

- Combination of eDRAM and other technologies – 3D stacking
- Exact combination depends on PCM bandwidths and latencies

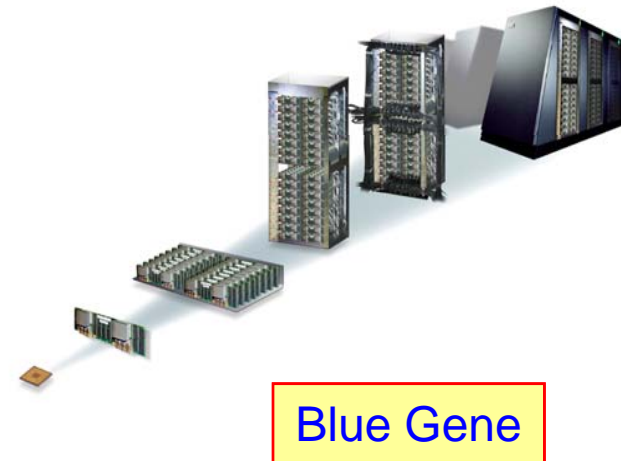
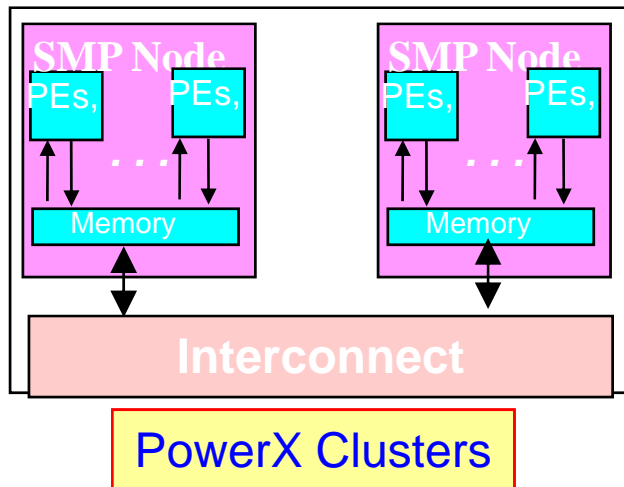
- **Interconnect: Need to make a very hard choice**

- Localized workloads: High degree toroidal interconnect with non-local “warps”
- Non-local workloads: Interconnect with broader reach

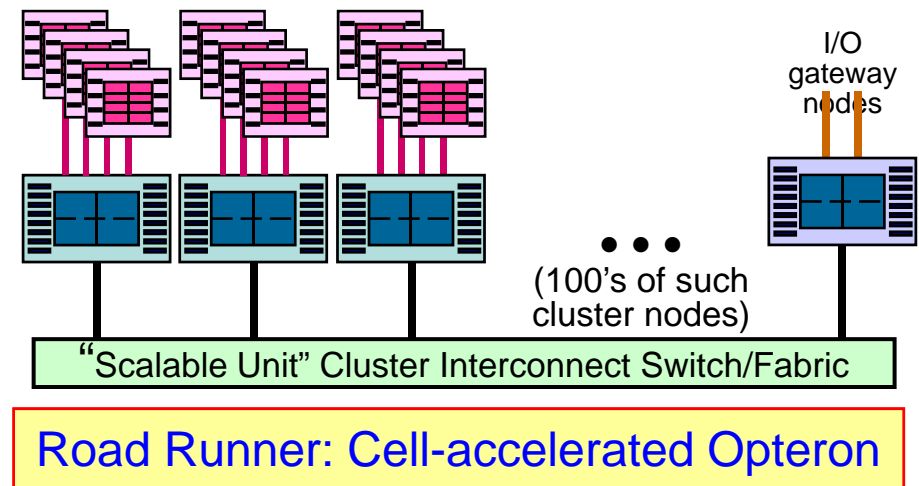
Productivity

Development and Execution time

The architectural landscape



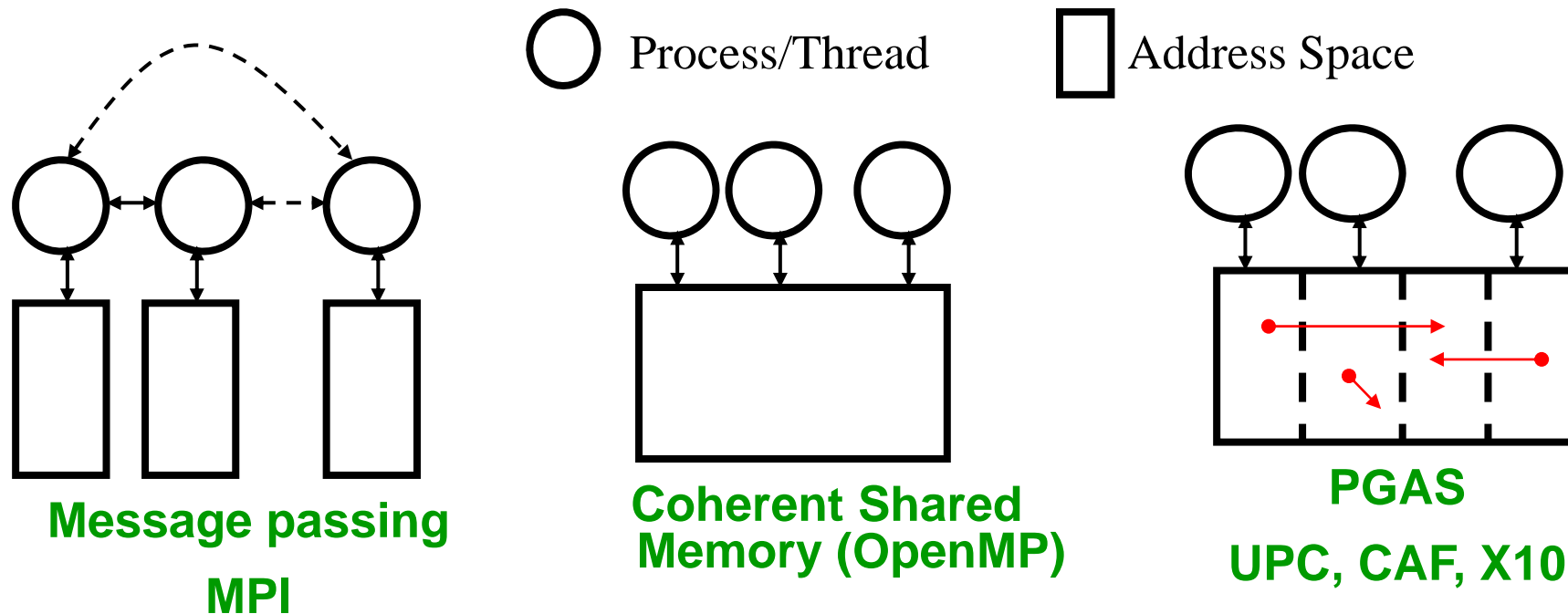
Multi-core processors, many with accelerators
 e.g. Sun Niagara
 e.g. Intel multicore, IXP
 e.g. IBM Cell
 e.g. GPGPUs



Multicore systems will dramatically raise the number of cores available to applications →
 Programmers must understand concurrent structure of their applications → Applications seeking to leverage these architectures will need to go beyond data-parallel, globally synchronizing MPI model.

Source: Vijay Saraswat, IBM Research

The Partitioned Global Address Space Model

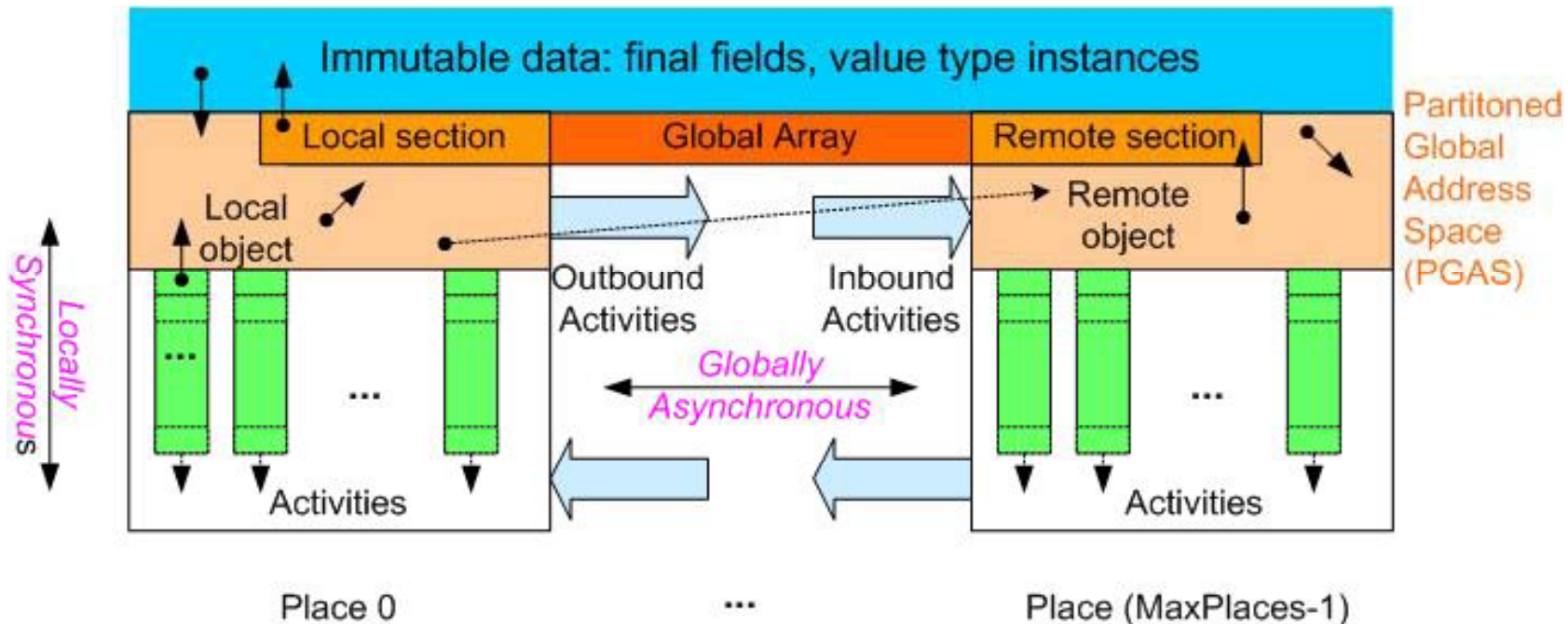


- Computation is performed in multiple **places**.
- A place contains data that can be operated on remotely.
- Data lives in the place it was created, for its lifetime.
- A datum in one place may reference a datum in another place.
- Data-structures (e.g. arrays) may be distributed across many places.
- Places may have different computational properties (e.g. PPE, SPE, ...).

A place expresses locality.

Source: Vijay Saraswat, IBM Research

X10: An Asynchronous PGAS language



■ Asynchrony

- Simple explicitly concurrent model for the user: **async (p) S** runs statement S “in parallel” at place p
- Controlled through **finish**, and local (conditional) **atomic**

- **Used for active messaging (remote asyncs), DMAs, fine-grained concurrency, fork/join concurrency, do-all/do-across parallelism**

- SPMD is a special case

Concurrency is made explicit and programmable.

Source: Vijay Saraswat, IBM Research

Concluding Thoughts

- **Getting to an exaflop system is going to be hard**
 - We need significant innovation in all system areas
- **Cost and power are going to be tremendous challenges**
 - How do we make it affordable?
 - How do we feed it?
- **Software and Hardware will need to work together to make system affordable**
- **Nothing like a good challenge to get things going!**